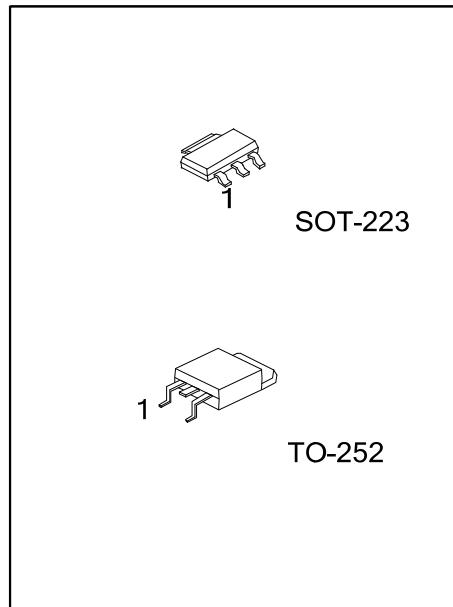
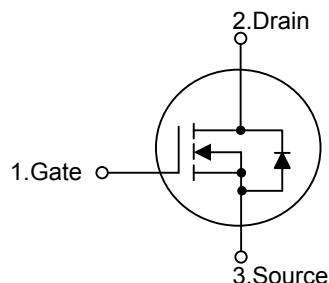


UTF3055**Power MOSFET****N-CHANNEL ENHANCEMENT
MODE POWER MOSFET****■ DESCRIPTION**

As an N-channel enhancement mode power MOSFET, the UTC **UTF3055** is designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

■ FEATURES

* $R_{DS(ON)} < 110 \text{ m}\Omega$ @ $V_{GS} = 10V$

■ SYMBOL**■ ORDERING INFORMATION**

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UTF3055L-AA3-R	UTF3055G-AA3-R	SOT-223	G	D	S	Tape Reel
UTF3055L-TN3-R	UTF3055G-TN3-R	TO-252	G	D	S	Tape Reel

UTF3055L-AA3-R	(1)Packing Type	(1) R: Tape Reel
	(2)Package Type	(2) AA3: SOT-223, TN3: TO-252
	(3)Lead Free	(3) G: Halogen Free, L:Lead Free

■ ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain Source Voltage		V_{DSS}	60	V
Drain Gate Voltage ($R_{GS} = 10\text{M}\Omega$)		V_{DGR}	60	V
Gate Source Voltage	Continuous	V_{GSS}	± 20	V
	Non-Repetitive ($t_P \leq 10\text{ ms}$)		± 30	V
Continuous Drain Current ($T_a = 25^\circ\text{C}$)		I_D	3.0	A
Pulsed Drain Current ($t_P \leq 10\text{ }\mu\text{s}$)		I_{DM}	9.0	A
Single Pulsed Avalanche Energy (Note 2)		EAS	74	mJ
Power Dissipation ($T_a = 25^\circ\text{C}$) (Note 3)	SOT-223	P_D	0.83	W
	TO-252		1.136	
Derate above 25°C	SOT-223		14	mW/ $^\circ\text{C}$
	TO-252		20	
Junction Temperature		T_J	175	$^\circ\text{C}$
Strong Temperature		T_{STG}	-55 ~ +175	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. $T_J = 25^\circ\text{C}$, $V_{DD} = 25\text{V}$, $V_{GS} = 10\text{V}$, $I_L = 7.0\text{A}$, $L = 3.0\text{mH}$, $V_{DS} = 60\text{V}$

3. When surface mounted to an FR4 board using 1" pad size, 1 oz.(Cu. Area 1.127 sq in).

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient (Note)	SOT-223	θ_{JA}	150	$^\circ\text{C/W}$
	TO-252		110	

Note: When surface mounted to an FR4 board using 1" pad size, 1 oz.(Cu. Area 1.127 sq in).

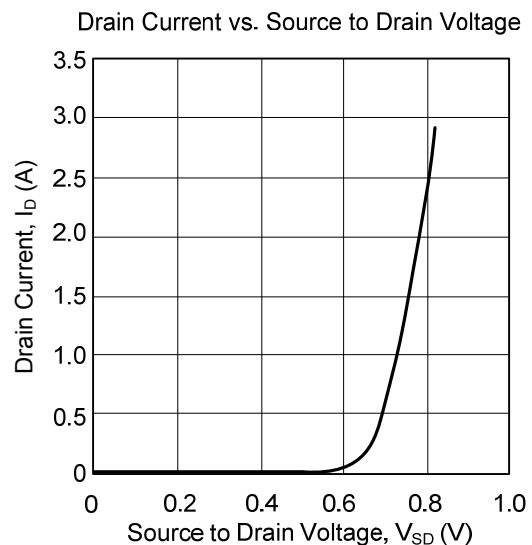
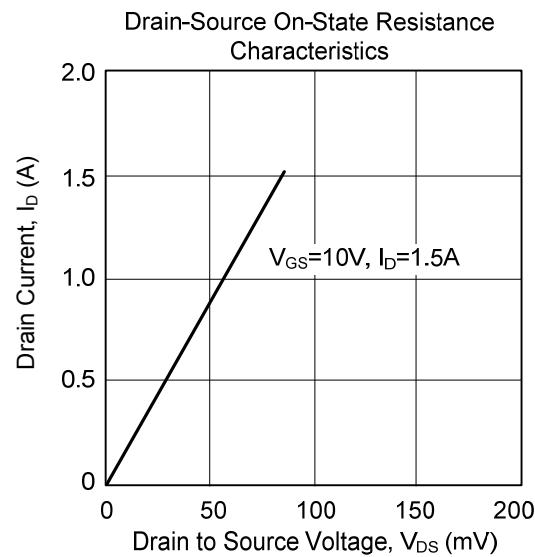
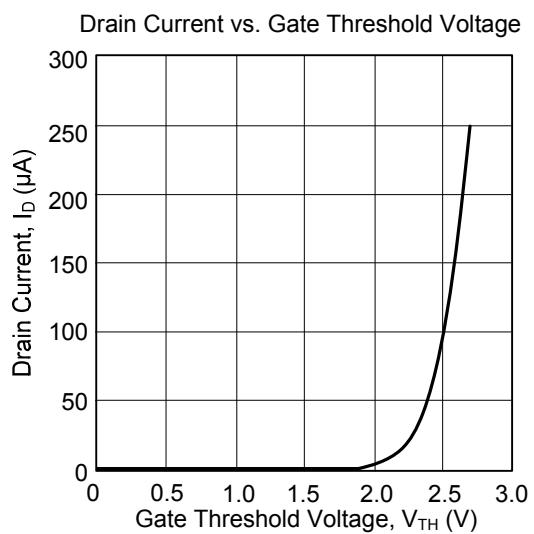
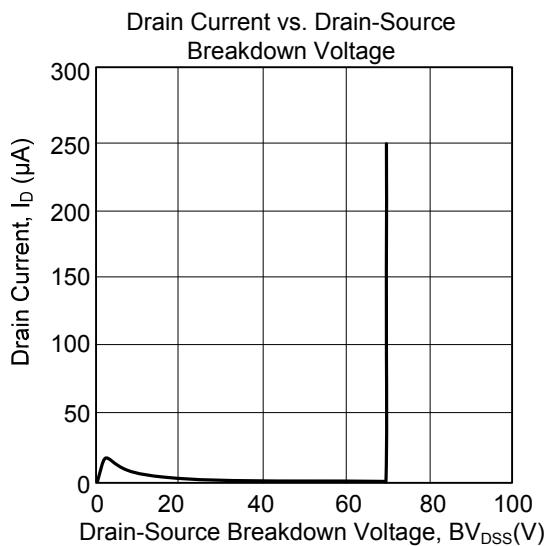
■ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain Source Breakdown Voltage (Note 1)	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	60	68		V
Temperature Coefficient (Positive)				66		$\text{mV}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 60\text{V}$			1.0	μA
Gate-Source Leakage Current	I_{GSS}	$ V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
ON CHARACTERISTICS (Note 1)						
Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 250\mu\text{A}$	2.0	3.0	4.0	V
Temperature Coefficient (Negative)				6.6		$\text{mV}/^\circ\text{C}$
Static Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 1.5\text{A}$		88	110	$\text{m}\Omega$
Static Drain-to-Source On-Resistance	$V_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 3\text{A}$		0.27	0.40	V
Forward Tran conductance	g_{FS}	$V_{\text{DS}} = 8.0\text{V}, I_{\text{D}} = 1.7\text{A}$		3.2		M
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$		324	455	pF
Output Capacitance	C_{OSS}			35	50	pF
Reverse Transfer Capacitance	C_{RSS}			110	155	pF
SWITCHING PARAMETERS (Note 2)						
Turn-ON Delay Time	$t_{\text{D(ON)}}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 30\text{V}, I_{\text{D}} = 3.0\text{A}, R_{\text{G}} = 9.1\Omega$ (Note 1)		9.4	20	ns
Turn-ON Rise Time	t_{R}			14	30	ns
Turn-OFF Delay Time	$t_{\text{D(OFF)}}$			21	45	ns
Turn-OFF Fall-Time	t_{F}			13	30	ns
Total Gate Charge	Q_{G}	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 48\text{V}, I_{\text{D}} = 3.0\text{A}$ (Note 1)		10.6	22	nC
Gate-Source Charge	Q_{GS}			1.9		nC
Gate-Drain Charge	Q_{GD}			4.2		nC
Diode Forward Voltage	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_{\text{S}} = 3.0\text{A}$		0.89	1.0	V
Body Diode Reverse Recovery Time	t_{RR}	$V_{\text{GS}} = 0\text{V}, I_{\text{S}} = 3.0\text{A}, dI/dt = 100\text{ A}/\mu\text{s}$ (Note 1)		30		ns
	t_{A}			22		ns
	t_{B}			8.6		ns
Body Diode Reverse Recovery Charge	Q_{RR}			0.04		nC

Note: 1. Pulse Test: Pulse Width $\leq 300\text{ s}$, Duty Cycle $\leq 2.0\%$.

2. Switching characteristics are independent of operating junction temperatures.

■ TYPICAL CHARACTERISTICS



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